

Polymer PTC Devices

Surface mount fuses

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LM130F

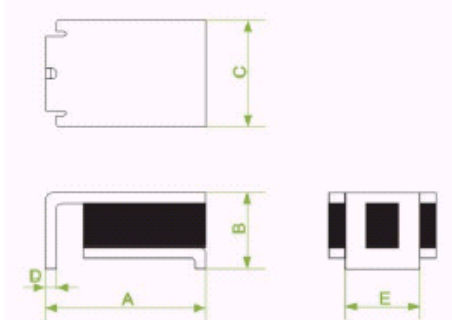
Features

- Surface mount devices
- Withstanding high interrupt voltage
- Lead-free and compliant with the European Union RoHS Directive 2011/65/EU
- Agency recognition: UL、TUV



Product Dimensions (mm)

Part number	A Typ.	B Typ.	C Typ.	D Typ.	E Typ.
LM130F	9.10±0.30	3.15±0.25	7.00±0.40	0.30±0.05	3.80±0.30



Marking system

LM □ □ □

Current rating

Product family

* Terminal materials: Tin-plated brass.

* Lead-free devices are available,
the right logo is lead-free mark of wayon.



Electrical Characteristics

Part number	I _H (A)	I _T (A)	Max. Time-to-trip Current(A) Time(s)	V _{max} (V)	I _{max} (A)	P _{d typ} (W)	R _{min} (Ω)	R _{max} (Ω)	R _{1max} (Ω)
LM130F	0.13	0.26	1.00 2.5	250	3.0	3.0	6.5	12.0	20.0

I_H=Hold current: maximum current at which the device will not trip at 25°C still air.

I_T=Trip current: minimum current at which the device will always trip at 25°C still air.

Max. Time-to-trip =Maximum time to trip(s) at assigned current.

V_{max}=Maximum voltage device can withstand without damage at rated current.

I_{max}=Maximum fault current device can withstand without damage at rated voltage.

P_{d typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min}=Minimum device resistance at 25°C prior to tripping.

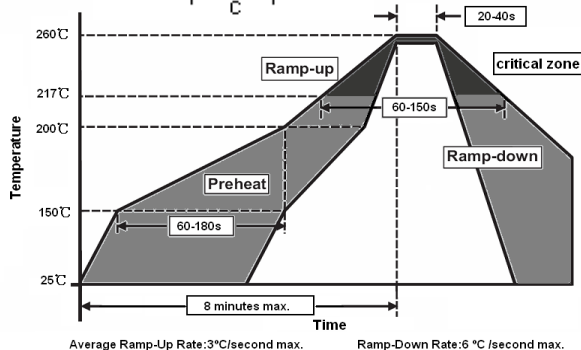
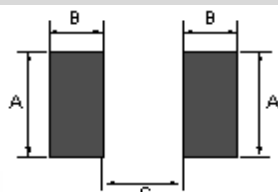
R_{max}=Maximum device resistance at 25°C prior to tripping.

R_{1max}=Maximum device resistance at 25°C one hour post trip.

Thermal Derating Chart-IH(A)

LM130F	Maximum ambient operating temperatures(°C)								
	-40	-20	0	25	40	50	60	70	85
Hold Current (A)	0.208	0.182	0.156	0.130	0.104	0.091	0.078	0.065	0.045
Trip Current (A)	0.416	0.364	0.312	0.260	0.208	0.182	0.156	0.130	0.090

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LM130F	4.6	1.8	6.1

* Recommended reflow methods: IR, Vapor phase oven, hot air oven.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requiremen

Package Information

Tape & Reel: 1500pcs per reel.